

SDS-500 "SINGLE"

"DRY" TYPE POU ABATEMENT

Exhaust solution for high-volume semiconductor manufacturing



Applications

- > Semiconductor processes

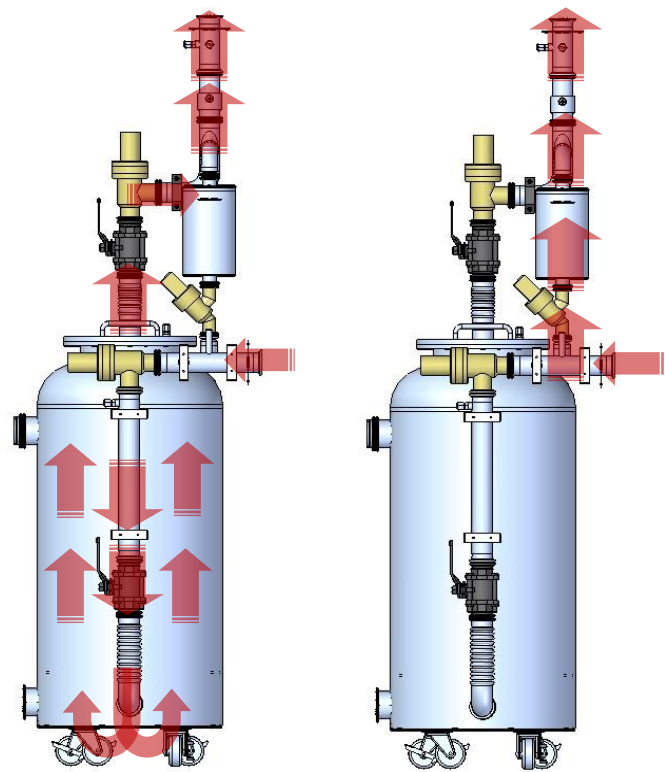
Features

- > Primary 80 liter cartridge
- > Bypass mini-cartridge
- > Standard N2 purge function
- > 80% color change sight tube
- > Double-acting pneumatic valves for power failure ride through
- > Pressure monitoring and relief
- > N2 eductor for inlet pressure control
- > Temperature monitoring and auto N2 purge function
- > Gas monitoring options
- > In-situ oxidation option

Benefits

- > Virtually zero unscheduled downtime with bypass cartridge
- > High abatement efficiency
- > Designed for target gas emissions level below TLV
- > Low overall CoO
- > HVM (high volume manufacturing) proven

System Specifications



Normal Operation

Bypass Operation

- Total System Capacity: **150 slm**
- MTBF: **>8,300 hours**
- MTTR: **<4 hour**
- MTTP: **<3 hour**

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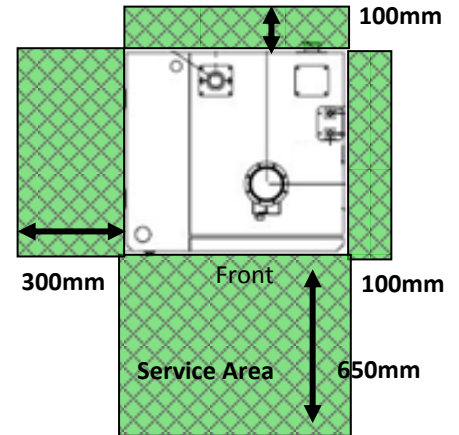
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Dimensions and Weight

SDS-500

Dimension (W x D x H in mm)	650 x 540 x 1650
Weight (kg)	250



Utilities

Item	Type	Typical Usage	Connection Type
Electricity	208VAC1 Phase	0.1 KW	5A
N2	3 ~ 6 kg/cm ²	40 LPM	1/4" SS compression
Air or N2	5 ~ 6.5 kg/cm ²	<0.1 LPM	1/4" SS compression (Valve Operation)
Gas Exhaust	-50 ~ -100 mmH2O	0.2 m ³ /min	KF40 Flange
Cabinet Exhaust	-50 ~ -60 mmH2O	1 m ³ /min	Ø100mm

Dry Media

Application	Adsorbent	Target Gas	Density
Acid gases	GST C1	Cl ₂ , BCl ₃ , HBr, HCl, HF	0.7
Basic gases	GST DB	NH ₃	0.75
Flammable gases	GST H2	SiH ₄ , PH ₃ , AsH ₃ , B ₂ H ₆ , DCS	0.9
VOC	GST M1	VOCs, NH ₃	0.75
Sulfide gases	GST DS	H ₂ S, SO ₂	0.7

- A combination of dry media may be used for optimum abatement efficiency and lifetime
- Other dry media types available

Environment

- Temperature: 5 ~ 30 °C
- Relative Humidity: < 65%